

Line Number	Hits	Search Text	DB	Time stamp
1	86	solder adj ball improve with wire with bond and (257/691).CCLS.	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/21 08:25
1	1	solder adj ball with improve with wire with bond	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/21 08:25
3	4	solder adj ball with improve with wire with bond	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/21 08:30
4	99	solder adj ball with wire with bond with connection	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/21 08:38
5	24	solder adj ball with wire with bond with lead	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/21 08:39
-	803	((257/691).CCLS.	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/19 16:28
-	220	((257/691).CCLS.) and power with line	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/17 18:17
-	208530	((257/691).CCLS.) and metallization with over coat	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/17 18:18
-	2	((257/691).CCLS.) and metallization with overcoat	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/17 18:19
-	19	((257/691).CCLS.) and metallization with (die IC semiconductor chip) with surface	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/17 18:44
-	6	5311055.URPN.	USPAT	2002/10/17 18:23
-	5	5751057.URPN.	USPAT	2002/10/17 18:25
-	14	"5222639" "5250840" "5252853" "5252454" "5266999" "5311055" "5358304" "5359224" "5365113" "5394008" "5428247" "5442233" "5461255" "5473190").PN.	USPAT	2002/10/17 18:26
-	51	5461255.URPN.	USPAT	2002/10/17 18:32
-	788	(257/691).CCLS.	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/17 18:47
-	10	((257/691).CCLS.) and metallization with die IC semiconductor chip with surface	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/10/17 18:47

-	789	(257/206).CCLS.	USPAT;	2002/10/17 16:47
			US-PGPUB;	
			EP; JPO;	
			DEFWENT;	
			IBM_TDB	
-	6	257/206).CCLS. and metallization with die IC semiconductor chip with surface	USPAT;	2002/10/17 16:47
			US-PGPUB;	
			EP; JPO;	
			DEFWENT;	
			IBM_TDB	
-	27	4249193.URPN.	USPAT	2002/10/17 16:49
-	4265	257/666	USPAT;	2002/10/18 10:48
			US-PGPUB;	
			EP; JPO;	
			DEFWENT;	
			IBM_TDB	
-	3666	(257/666).CCLS.	USPAT;	2002/10/18 10:48
			US-PGPUB;	
			EP; JPO;	
			DEFWENT;	
			IBM_TDB	
-	1059	((257/666).CCLS.) AND(metallization lead line bus WITH (chip die ic semiconductor integrated adj circuit)WITH surface	USPAT;	2002/10/18 10:52
			US-PGPUB;	
			EP; JPO;	
			DEFWENT;	
			IBM_TDB	
-	842	((257/666).CCLS.) AND(metallization lead line bus WITH (chip die ic semiconductor integrated adj circuit)WITH surface) AND wire AND lead	USPAT;	2002/10/18 10:52
			US-PGPUB;	
			EP; JPO;	
			DEFWENT;	
			IBM_TDB	
-	796	((257/666).CCLS.) AND(metallization lead line bus WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and wire WITH lead	USPAT;	2002/10/18 10:53
			US-PGPUB;	
			EP; JPO;	
			DEFWENT;	
			IBM_TDB	
-	30	((257/666).CCLS.) AND(metallization lead line bus WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and wire WITH lead) AND active WITH element	USPAT;	2002/10/18 11:04
			US-PGPUB;	
			EP; JPO;	
			DEFWENT;	
			IBM_TDB	
-	8	"5148664" "5150828" "5205463" "5710407" "5717252" "5803246" "5812318" "5838225").PN.	USPAT	2002/10/18 10:55
-	13	"4156382" "4362245" "4948754" "511711" "5252853" "5331200" "5344487" "5538920" "5565379" "5589964" "5578526" "5587336" "5677587").PN.	USPAT	2002/10/18 10:59
-	14	5384481.URPN.	USPAT	2002/10/18 11:01
-	155	((257/666).CCLS.) AND(metallization lead line bus WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and wire WITH lead) AND encapsulate	USPAT;	2002/10/18 11:35
			US-PGPUB;	
			EP; JPO;	
			DEFWENT;	
			IBM_TDB	
-	7	"5157182" "5428248" "5834837" "5893216" "5977613" "5998877" "6329715").PN.	USPAT	2002/10/18 11:08
-	1	"4546374").PN.	USPAT	2002/10/18 11:12
-	11	4546374.URPN.	USPAT	2002/10/18 11:12
-	26	5322843.URPN.	USPAT	2002/10/18 11:34
-	4	"4719300" "5574297" "5640024" "5777331").PN.	USPAT	2002/10/18 11:41
-	2	6144100.PN.	USPAT;	2002/10/18 13:55
			US-PGPUB;	
			EP; JPO;	
			DEFWENT;	
			IBM_TDB	

-	6134621.PN.	USPAT;	2002/10/18 13:56
-		US-PGPUB;	
-		EPO; JPO;	
-		DERWENT;	
-		IBM_TDB	
-	9 ("5462894" "5575524" "5666061" "5736821" "5843516" "5851968" "5866698" "5994027" "6146113").PN.	USPAT	2002/10/18 13:56
-	971 word with line with power with ground	USPAT;	2002/10/18 14:53
-		US-PGPUB;	
-		EPO; JPO;	
-		DERWENT;	
-		IBM_TDB	
-	121 (word with line with power with ground) AND (257/691).CCLS.	USPAT;	2002/10/18 14:53
-		US-PGPUB;	
-		EPO; JPO;	
-		DERWENT;	
-		IBM_TDB	
-	9 6066515.URPN.	USPAT	2002/10/18 18:29
-	8 ("5148964" "5150828" "5205463" "5710457" "5717252" "5803246" "5872338" "5898225").PN.	USPAT	2002/10/18 18:37
-	813 (257/691).CCLS.	USPAT;	2002/10/18 18:39
-		US-PGPUB;	
-		EPO; JPO;	
-		DERWENT;	
-		IBM_TDB	
-	32 ((257/691).CCLS.) and power with lines with surface	USPAT;	2002/10/18 18:52
-		US-PGPUB;	
-		EPO; JPO;	
-		DERWENT;	
-		IBM_TDB	
-	3 ("5028983" "5256996" "5550406").PN.	USPAT	2002/10/18 18:43
-	4 5677570.URPN.	USPAT	2002/10/18 18:44
-	33 ("4355456" "4878098" "4916519" "4948754" "4949150" "4993305" "4993618" "5009721" "5061985" "5062351" "5226582" "5235212" "5319224" "5441917" "5463255" "5502337" "5523628" "5587607" "5602420" "5608245" "5612570" "5623154" "5637920" "5640048" "5641978" "5644166" "5652467" "5666008" "5677570" "5693984" "5712508" "5731634" "5742100").PN.	USPAT	2002/10/18 18:47
-	759 (257/208).CCLS.	USPAT;	2002/10/18 18:52
-		US-PGPUB;	
-		EPO; JPO;	
-		DERWENT;	
-		IBM_TDB	
-	236 (257/209).CCLS.	USPAT;	2002/10/18 18:52
-		US-PGPUB;	
-		EPO; JPO;	
-		DERWENT;	
-		IBM_TDB	
-	11 (257/208).CCLS.) and power with lines with surface	USPAT;	2002/10/18 18:55
-		US-PGPUB;	
-		EPO; JPO;	
-		DERWENT;	
-		IBM_TDB	
-	1 (257/209).CCLS.) and power with lines with surface	USPAT;	2002/10/18 18:55
-		US-PGPUB;	
-		EPO; JPO;	
-		DERWENT;	
-		IBM_TDB	
-	1 (257/209).CCLS.) and power with line with surface	USPAT;	2002/10/18 18:56
-		US-PGPUB;	
-		EPO; JPO;	
-		DERWENT;	
-		IBM_TDB	

-	3066	(257/666).CCLS.	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/18 18:18
-	13	((257/666).CCLS.) and power with line with surface	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/18 18:27
-	183	((257/666).CCLS.) and line with surface	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/18 18:11
-	661	power ground with line with surface and 257/9.ccls.	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/18 18:12
-	88	((power ground)with line with surface and 257/9.ccls.) and lead with frame	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/18 19:26
-	2	5973554.pn.	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/21 08:22
-	2	6144100.pn.	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/19 16:35
-	4	("5182420" ! "5367195" ! "5369220" - "5734200").PN.	USPAT	2002/10/19 16:40
-	3066	(257/666).CCLS.	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/19 17:53
-	3	((257/666).CCLS.) and art with lead with frame with mounting with pad	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/19 18:13
-	5	conventionally with mounting with pad with lead adj frame and (257/9).ccls.	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/19 18:15
-	6	conventionally with mounting with pad with lead adj frame	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/19 18:16
-	11	conventionally with die with pad with lead adj frame	USPAT; US-PGPUB; EPC; JPC; DEFWENT; IBM_TDB	2002/10/19 18:16